REMARKS ·

Claims 1-11 and 33-38 are pending.

Claims 1-4 stand rejected under 35 USC §103(a) as being allegedly unpatentable over <u>Furuya</u> et al (US 6,084,215) in view of <u>Kholodenko</u> et al (US 6,310,755).

Claims 5-9 and 33-38 stand rejected under 35 USC §103(a) as being allegedly unpatentable over <u>Furuya</u> et al (US 6,084,215) in view of <u>Kholodenko</u> et al (US 6,310,755) and further in view of <u>Mahawili</u> (US 5,059,770) or <u>Carman</u> et al (US 5,294,778).

Claim 10 stands rejected under 35 USC §103(a) as being allegedly unpatentable over <u>Furuya</u> et al (US 6,084,215) in view of <u>Kholodenko</u> et al (US 6,310,755) and further in view of <u>Weber</u> (US 4,518,848).

Claim 11 stands rejected under 35 USC §103(a) as being allegedly unpatentable over <u>Furuya</u> et al (US 6,084,215) in view of <u>Kholodenko</u> et al (US 6,310,755) and further in view of <u>Yoshida</u> (US 6,080,970).

Rejection under 35 USC §103(a) – claims 1-4

Claims 1-4 stand rejected under 35 USC §103(a) as being allegedly unpatentable over <u>Furuya</u> et al (US 6,084,215) in view of <u>Kholodenko</u> et al (US 6,310,755). This rejection is respectfully traversed.

Under MPEP §706.02(j), in order to establish a prima facie case of obviousness required for a §103 rejection, three basic criteria must be met: (1) there must be some suggestion or motivation either in the references or knowledge generally available to

modify the reference or combine reference teachings (MPEP §2143.01), (2) a reasonable expectation of success (MPEP §2143.02), and (3) the prior art must teach or suggest all the claim limitations (MPEP §2143.03). See <u>In re Royka</u>, 490 F. 2d 981, 180 USPQ 580 (CCPA 1974).

<u>Furuya</u> describes a spring-mounted temperature measurement apparatus disposed within a wafer holder. Further, <u>Furuya</u> describes measuring the temperature of a wafer in **absence of a plasma process** in a wafer storage chamber (FIG. 1).

Kholodenko describes a heater 235 embedded in the base 175 rather than in the dielectric 115 of the electrostatic member 100. See col. 10, lines 22-24. Kholodenko teaches away from a flat support having a heater embedded therein as presently claimed in the present application (see claim 1).

1. There is no justification in <u>Furuya</u> or in <u>Kholodenko</u>, which suggests that both references be combined in the manner proposed.

Applicants respectfully assert that there is no impetus to combine <u>Furuya</u> with <u>Kholodenko</u> in the manner proposed. First, with regard to the modification of <u>Furuya</u> and <u>Kholodenka</u>, it is well known that in order for any prior-art reference to be validly modified for use in a prior-art §103 rejection, the reference itself must suggest the desire for modification. E.g., as was stated in <u>In re Fritch</u>, 972 F.2d 1260, 1266, 23 USPQ 2d 1780, 1783-84 (Fed. Cir. 1992):

The mere fact that the prior art may be modified in the manner suggested by the Examiner does not make the modification obvious unless the prior art suggested the desirability of the modification.

Application No.: 09/846,432 Amendment dated October 29, 2003 Reply to Final Office Action of July 29, 2003

Turning now to the cited art, <u>Furuya</u> describes an apparatus for measuring the temperature of a wafer "in an electrical characteristic test and reliability test for chips." Col. 2, lines 44-45.

It should be clear that the addition of plasma to anything in <u>Furuya</u> will alter if not destroy a wafer. Thus, plasma cannot be introduced in <u>Furuya</u> without obliterating its intended purpose.

Further, Furuya states that "in carrying a reliability test for a wafer, a wafer W is integrated with a contactor 3 into a single entity on a wafer holding table. In this state, each wafer is put into each wafer **storage chamber** 1." Col. 7, lines 6-10. "In the temperature control compartment 1A, a base 5 is provided." Col. 7, line 30. "Between the base 5 and pressure plate 7, a support plate 8 is provided in parallel with the base 5". Col. 7, lines 40-41. The storage chamber described in <u>Furuya</u> does not include any additional heating flux from a plasma process. In particular, <u>Furuya</u> describes a support plate 8 that includes a bottom jacket 9 in a temperature control compartment 1A of a **wafer storage chamber** 1 in the **absence of a plasma process**. As pointed in the Final Office Action at page 2, <u>Furuya</u> does not teach or suggest a flat support **receiving an incoming flux from a plasma during a process**.

Furthermore, Applicants believe that in fact <u>Furuya</u> teaches away from "receiving an incoming flux from a plasma during a process" because the apparatus disclosed in <u>Furuya</u> is for measuring the temperature of a wafer **outside a plasma process**.

As shown in FIG. 1, the wafer storage chamber 1 is composed of a temperature control compartment 1A and a connector compartment 1B adjacent to the temperature control compartment 1A. Between the compartments 1A and 1B, a heat insulation wall (not shown) is provided. The heat insulation wall prevents the rise of the temperature in the connector compartment 1B as much as possible. In

Application No.: 09/846, 32 Amendment dated October 29, 2003 Reply to Final Office Action of July 29, 2003

the temperature control compartment 1A, the temperature of the wafer W is kept at a test temperature and the temperate around the wafer W is forced to rise as little as possible.

Furuya, Col. 7, lines 19-29. (emphasis added).

Moreover, the wafer W in <u>Furuya</u> is kept at a specific test temperature.

In this state, the bottom jacket 9 controls the temperature of the wafer chuck 2 to keep the temperature of the wafer W at a specific test temperature (e.g., 110°C).

Furuya, Col. 7, lines 64-67. (emphasis added).

Plasma, on the other hand, implicates operating temperature far above those cited in <u>Furuya</u>. Thus, because the apparatus of <u>Furuya</u> operates at a test temperature of 110°C far from the several hundreds of degrees Celsius under a plasma process, the apparatus of <u>Furuya</u> is not designed for use **during a process in a plasma chamber**. Therefore, one of ordinary skill in the art would not have combined the teachings of <u>Furuya</u> and Kholodenka.

Thus, Applicant submits that there is no motivation to combine the teachings of Furuya and Kholodenka and respectfully requests the rejection be withdrawn.

2. Even if <u>Furuya</u> and <u>Kholodenko</u> were to be combined in the manner proposed, there is no reasonable expectation of success for the suggested combination.

Even if the teachings of <u>Furuya</u> and <u>Kholodenko</u> were combined in the manner proposed, the suggested combination would be inoperable. As explained above, the apparatus taught in <u>Furuya</u> operates at a test temperature in the range of 110°C. In contrast, <u>Kholodenko</u> teaches that the "electrostatic member 100 and base 175 are heated to a temperature of up to 600°C." The "electrostatic chuck 55 and the plug 345 are

maintained at a temperature of about 600°C." See <u>Kholodenko</u>, Col. 9, lines 50-51; Col. 14, lines 46-47. The final office action contends that "it would have been obvious to one of ordinary skill in the art of <u>Furuya</u> with the plasma heating flux as an additional heating means to further provide the uniform heat across the chuck." Page 2 of the Final Office Action.

Contrary to the above assertions of the Final Office Action, the introduction of plasma heating flux to the apparatus of <u>Furuya</u> would render the apparatus inoperable. Several components (such as the seal ring 24 made of silicone rubber, the silicone rubber film 25, the O ring 27, etc...) in <u>Furuya</u> would completely melt under the extremely high temperature (600°C as taught by <u>Kholodenko</u>) created by the plasma heating flux. Thus, the apparatus of <u>Furuya</u> when combined with the teachings of <u>Kholodenko</u> would be inoperable.

Thus, Applicant submits that there is no reasonable expectation for success for the suggested combination of <u>Furuya</u> and <u>Kholodenko</u> and respectfully requests the rejection be withdrawn.

Rejection under 35 USC §103(a) - claims 5-9 and 33-38

Claims 5-9 and 33-38 stand rejected under 35 USC §103(a) as being allegedly unpatentable over <u>Furuya</u> et al (US 6,084,215) in view of <u>Kholodenko</u> et al (US 6,310,755) and further in view of <u>Mahawili</u> (US 5,059,770) or <u>Carman</u> et al (US 5,294,778). This rejection is respectfully traversed.

These rejections are respectfully traversed for at least the reason that each of the rejected claims ultimately depend on an above-discussed allowable base claim. The

arguments set forth above regarding the base claims are equally applicable here. The base claims being allowable, the dependent claims must also be allowable. Therefore, applicant respectfully requests the rejection be withdrawn.

Rejection under 35 USC §103(a) - claim 10

Claim 10 stands rejected under 35 USC §103(a) as being allegedly unpatentable over <u>Furuya</u> et al (US 6,084,215) in view of <u>Kholodenko</u> et al (US 6,310,755) and further in view of <u>Weber</u> (US 4,518,848). This rejection is respectfully traversed.

These rejections are respectfully traversed for at least the reason that each of the rejected claims ultimately depend on an above-discussed allowable base claim. The arguments set forth above regarding the base claims are equally applicable here. The base claims being allowable, the dependent claims must also be allowable. Therefore, applicant respectfully requests the rejection be withdrawn.

Rejection under 35 USC §103(a) - claim 11

Claim 11 stands rejected under 35 USC §103(a) as being allegedly unpatentable over <u>Furuya</u> et al (US 6,084,215) in view of <u>Kholodenko</u> et al (US 6,310,755) and further in view of <u>Yoshida</u> (US 6,080,970). This rejection is respectfully traversed.

These rejections are respectfully traversed for at least the reason that each of the rejected claims ultimately depend on an above-discussed allowable base claim. The arguments set forth above regarding the base claims are equally applicable here. The base claims being allowable, the dependent claims must also be allowable. Therefore, applicant respectfully requests the rejection be withdrawn.

LAM-P0808 032747-010

Application No.: 09/846, 32 Amendment dated October 29, 2003 Reply to Final Office Action of July 29, 2003

Conclusion

For all of the above reasons, applicants submit that the amended claims are now in proper form, and that the amended claims all define patentable subject matter over the prior art. Therefore, Applicants submit that this application is now in condition for allowance.

Request for allowance

It is believed that this Amendment places the above-identified patent application into condition for allowance. Early favorable consideration of this Amendment is earnestly solicited. If, in the opinion of the Examiner, an interview would expedite the prosecution of this application, the Examiner is invited to call the undersigned attorney at the number indicated below.

Respectfully submitted, THELEN REID & PRIEST LLP

Dated: October $\frac{20}{3}$, 2003

Reg. No. 49,097

Thelen Reid & Priest LLP P.O. Box 640640 San Jose, CA 95164-0640 (408) 282-1810 Direct (408) 292-5800 Main (408) 287-8040 Fax